

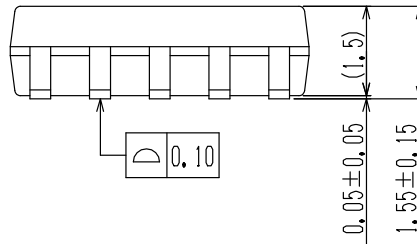
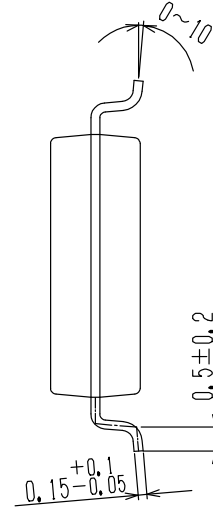
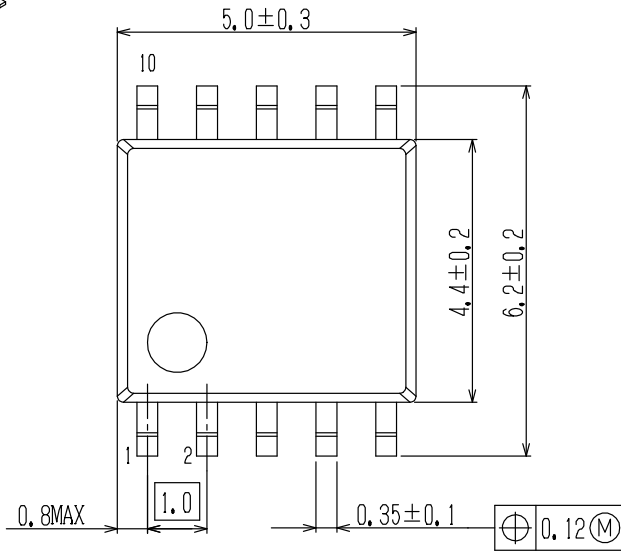
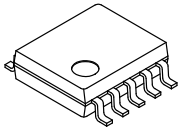
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®

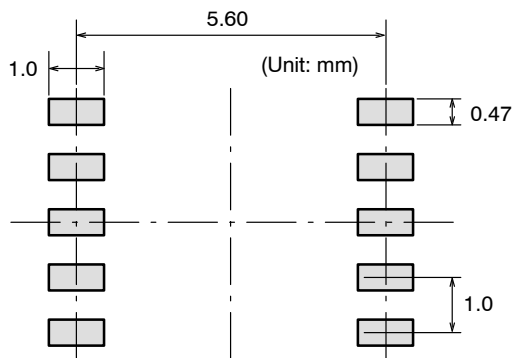


**SOIC10W / MFP10SK (225 mil)**  
**CASE 751DA**  
**ISSUE A**

DATE 23 OCT 2013



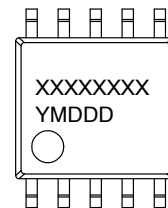
**SOLDERING FOOTPRINT\***



NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC MARKING DIAGRAM\***



XXXX = Specific Device Code  
 Y = Year  
 M = Month  
 DDD = Additional Traceability Data

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

|                         |                                    |  |
|-------------------------|------------------------------------|--|
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| <b>STATUS:</b>          | <b>ON SEMICONDUCTOR STANDARD</b>   |  |
| <b>NEW STANDARD:</b>    |                                    |  |
| <b>DESCRIPTION:</b>     | <b>SOIC10W / MFP10SK (225 MIL)</b> | <b>PAGE 1 OF 2</b>   |

